

Description

The DFH100FB12P3H1 offer lower losses and higher energy for application such as motor drive, inverter and soft switching applications.

Features

- 1200V100 A, $V_{CE(sat)}(typ.) = 1.40V$
- Lower losses and higher energy
- Excellent short-circuit capability
- Zero Reverse Recovery from SiC Diodes



Applications

- Motor drive
- Inverter
- Welding machines
- UPS

Circuit diagram

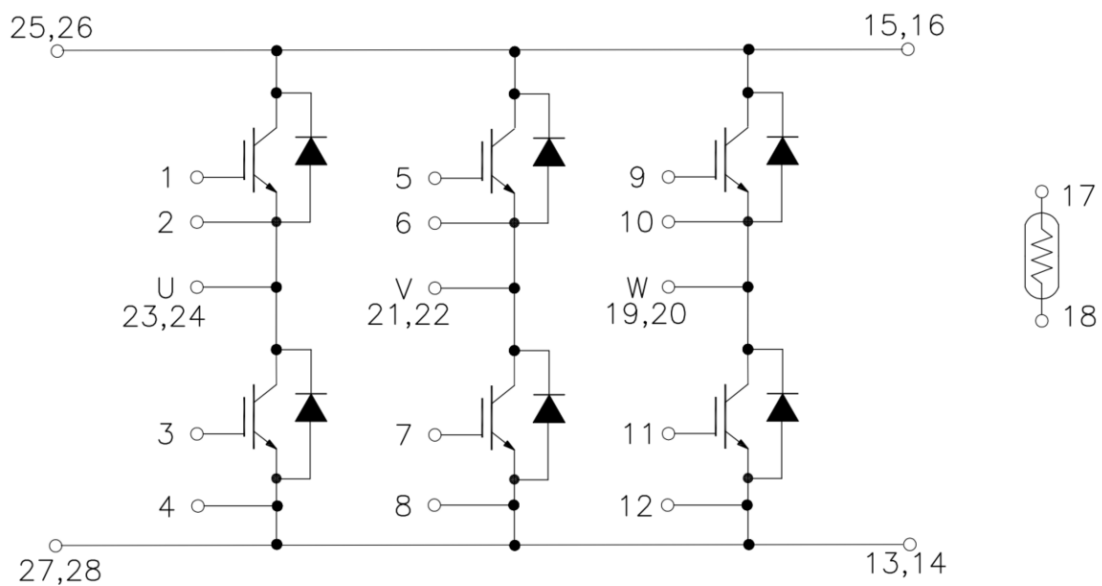


Figure 1. Out drawing & circuit diagram for DFH100FB12P3H1

Pin Configuration and Marking Information

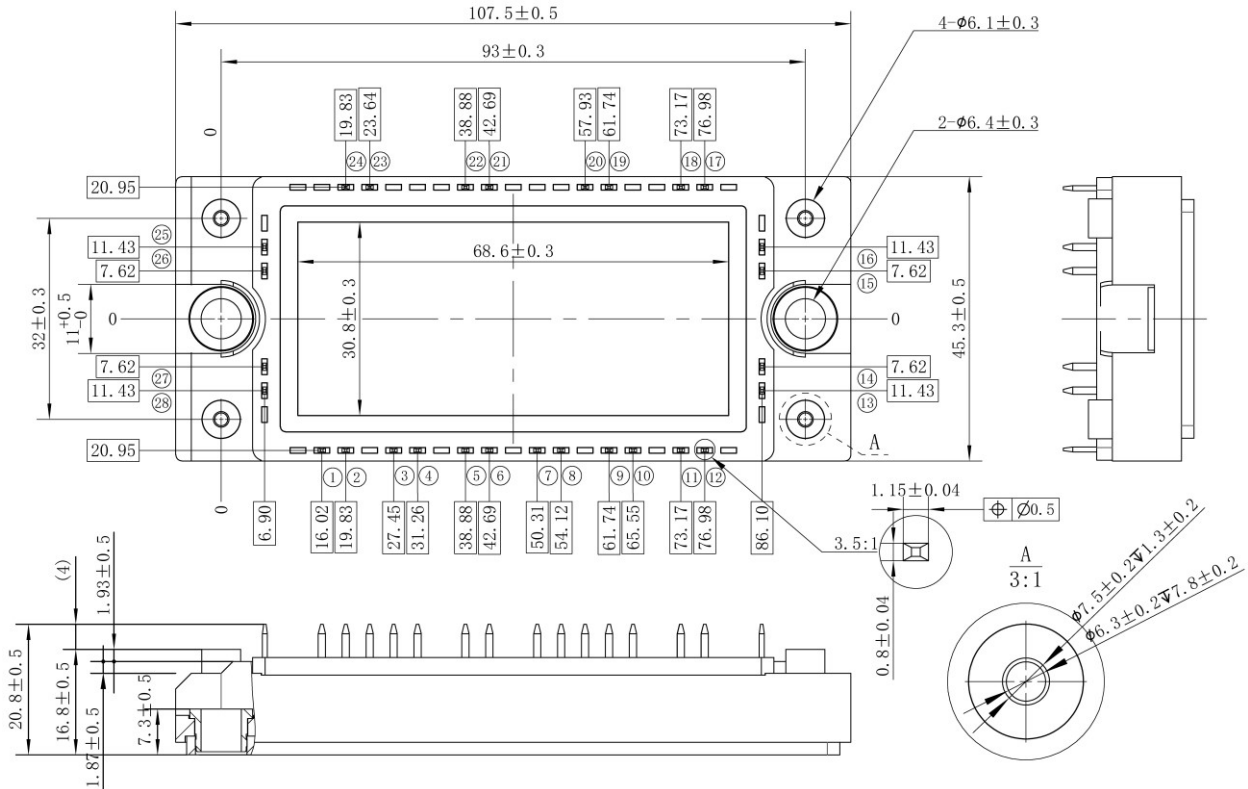


Figure 2. Pin configuration

Module

Parameter	Conditions	Value	Unit
Isolation Voltage	RMS, f = 50Hz, t = 1min	2.5	KV
CTI	-	>200	-
Module lead resistance, terminals – chip	T _c = 25°C	0.8	mΩ
Mounting torque for module mounting	M5	3.5	Nm
Weight	-	175	g

Maximum Ratings ($T_j=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Ratings	Unit
V_{CES}	Collector-Emitter Voltage	G-E Short	1200	V
V_{GES}	Gate-Emitter Voltage	C-E Short	$\pm 20\text{V}$	V
I_C	DC Continuous Collector Current	$T_C=120^\circ\text{C}$, $T_{vjop}=150^\circ\text{C}$ (IGBT)	100	A
I_{CM}	Pulse Collector Current	$t_p=1\text{ms}$, Note1	200	A
P_C	Maximum Power Dissipation	$T_C=25^\circ\text{C}$, $T_{vjop}=150^\circ\text{C}$ (IGBT)	625	W
I_F	Diode forward Current	-	100	A
I_{FRM}	Repetitive peak forward Current	$t_p=1\text{ms}$, Note1	200	A
t_{sc}	Short Circuit Withstand Time	$V_{GE}=15\text{V}$, $V_{CE}=600\text{V}$	10	μs
T_{jmax}	Max junction temperature	-	175	$^\circ\text{C}$
T_{vjop}	Operating junction temperature	-	-40 to 150	$^\circ\text{C}$
T_{stg}	Storage temperature	-	-40 to 125	$^\circ\text{C}$

Note1: Pulse width limited by maximum junction temperature

NTC characteristics

Symbol	Parameter	Condition	Value			Unit
			Min.	Typ.	Max.	
R_{25}	Resistance	$T_C=25^\circ\text{C}$	-	5	-	$\text{k}\Omega$
$\Delta R/R$	Deviation of R_{100}	$T_C=100^\circ\text{C}$, $R_{100}=493\Omega$	-5	-	5	%
P_{25}	Power dissipation	$T_C=25^\circ\text{C}$	-	-	20	mW
$B_{25/50}$	B-value	$R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298,15 \text{ K}))]$	-	3375	-	K
$B_{25/80}$	B-value	$R_2 = R_{25} \exp [B_{25/80}(1/T_2 - 1/(298,15 \text{ K}))]$	-	3411	-	K
$B_{25/100}$	B-value	$R_2 = R_{25} \exp [B_{25/100}(1/T_2 - 1/(298,15 \text{ K}))]$	-	3433	-	K

IGBT Electrical characteristics (T_j=25°C unless otherwise specified, chip)

Symbol	Item	Condition		Value			Unit
				Min.	Typ.	Max.	
V _{CE(sat)}	Collector-Emitter Saturation Voltage	I _C =100A V _{GE} =15V	T _j =25°C	-	1.30	-	V
			T _j =125°C	-	1.42	-	V
			T _j =150°C	-	1.45	-	V
			T _j =175°C	-	1.50	-	V
V _{GE(th)}	Gate-Emitter threshold Voltage	I _C =5.7mA, V _{CE} =V _{GE}		5.0	5.8	6.5	V
Q _G	Gate charge	V _{GE} = -15V to +15V		-	1728	-	nC
R _{Gint}	Internal gate resistor	-	T _j =25°C	-	2.1	-	Ω
C _{ies}	Input Capacitance	V _{CE} =25V	T _j =25°C	-	21.6	-	nF
C _{oes}	Output Capacitance	V _{GE} =0V		-	0.59	-	nF
C _{res}	Reverse transfer Capacitance	f=1MHz		-	0.17	-	nF
I _{CES}	Collector- Emitter Cut off Current	V _{CE} =1200V, V _{GE} =0V	T _j =25°C	-	-	1	mA
I _{GES}	Gate-Emitter Leakage Current	V _{GE} =20V, V _{CE} =0V	T _j =25°C	-	-	1	μA
t _{d(on)}	Turn-on delay time	V _{CC} =600V I _C =100A V _{GE} =+15V/-8V R _{Gon} = R _{Goff} =4.7Ω Inductive load	T _j =25°C	-	212	-	ns
			T _j =125°C	-	210	-	
			T _j =150°C	-	209	-	
t _r	Rise time		T _j =25°C	-	22	-	ns
			T _j =125°C	-	33	-	
			T _j =150°C	-	37	-	
t _{d(off)}	Turn-off delay time		T _j =25°C	-	457	-	ns
			T _j =125°C	-	532	-	
			T _j =150°C	-	549	-	
t _f	Fall time	T _j =25°C	-	216	-	ns	
		T _j =125°C	-	348	-		
		T _j =150°C	-	401	-		
E _{on}	Turn-on power dissipation	T _j =25°C	-	3.99	-	mJ	
		T _j =125°C	-	5.34	-		
		T _j =150°C	-	5.70	-		
E _{off}	Turn-off power dissipation	T _j =25°C	-	10.21	-	mJ	
		T _j =125°C	-	14.23	-		
		T _j =150°C	-	15.27	-		
R _{th(j-c)}	Thermal Resistance, Junction to Case (IGBT)		-	0.20	-	K/W	
R _{th(c-s)}	Thermal Resistance, Case to sink (Conductive Grease applied)		-	0.05	-	K/W	

SiC SBD Electrical characteristics (T_j=25°C unless otherwise specified, chip)

Symbol	Item	Condition	Value			Unit	
			Min.	Typ.	Max.		
V _F	Diode Forward Voltage	I _F =100A, V _{GE} =0V	T _j =25°C	-	1.65	-	V
			T _j =125°C	-	2.15	-	
			T _j =150°C	-	2.35	-	
			T _j =175°C	-	2.55	-	
t _{rr}	Diode Reverse Recovery Time	(Switch side) V _{CC} =600V, I _C =100A V _{GE} =+15V/-8V	T _j =25°C	-	22	-	ns
			T _j =125°C	-	33	-	
			T _j =150°C	-	32	-	
Q _{rr}	Recovered charge	R _{Gon} = R _{Goff} =4.7Ω (SiC SBD side) V _{rr} =600V, I _F =100A	T _j =25°C	-	0.597	-	μC
			T _j =125°C	-	0.444	-	
			T _j =150°C	-	0.464	-	
E _{rr}	Reverse recovered energy	V _{GE} =-8V Inductive load switching operation	T _j =25°C	-	0.195	-	mJ
			T _j =125°C	-	0.114	-	
			T _j =150°C	-	0.104	-	
R _{th(j-c)}	Thermal Resistance, Junction to Case (SiC SBD)		-	0.45	-	K/W	
R _{th(c-s)}	Thermal Resistance, Case to sink (Conductive Grease applied)		-	0.05	-	K/W	

Test Conditions

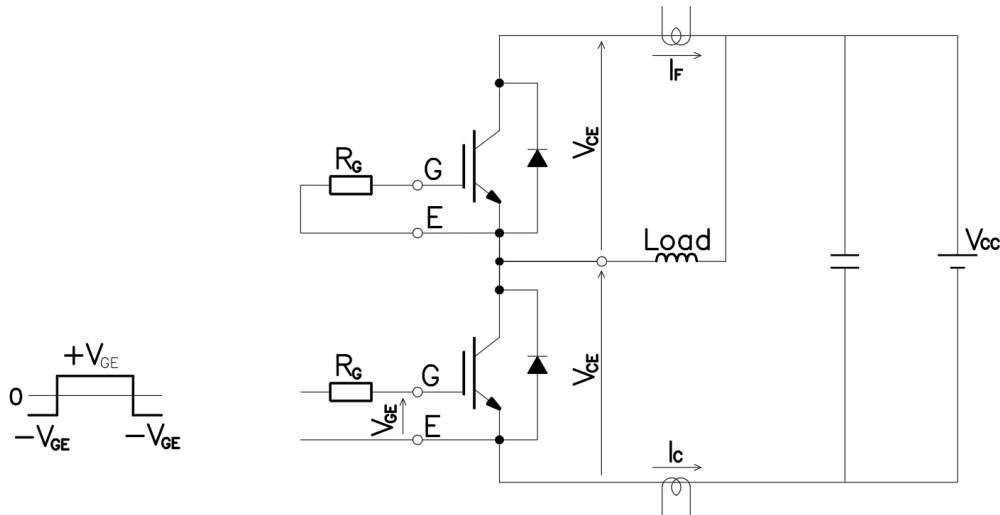


Figure 3. Switching time measure circuit

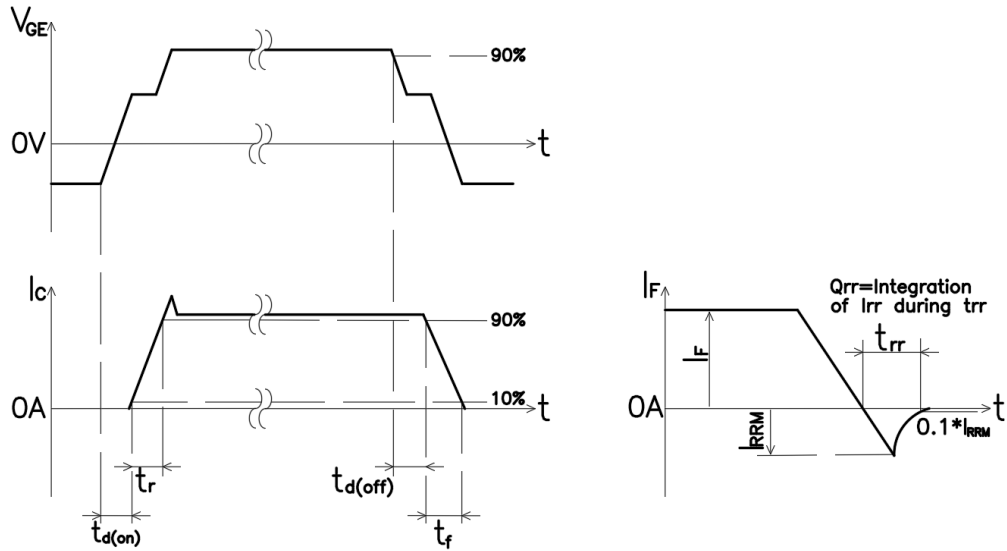
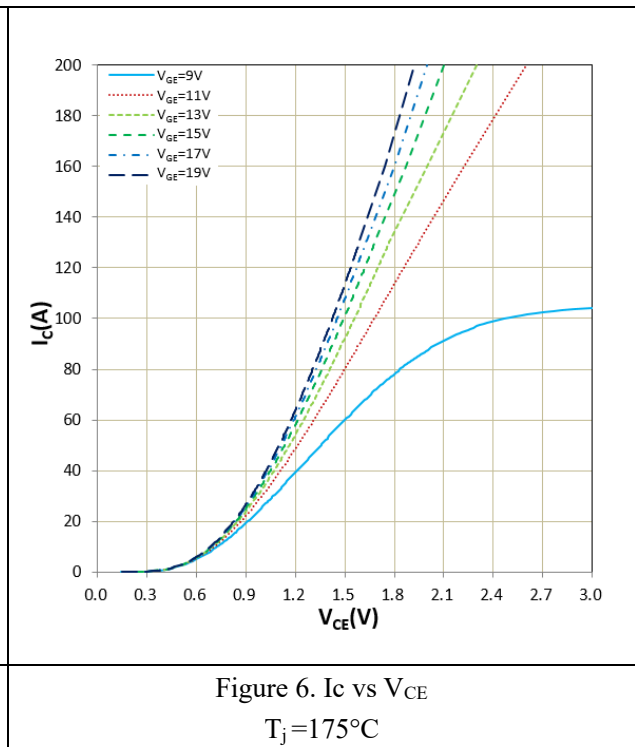
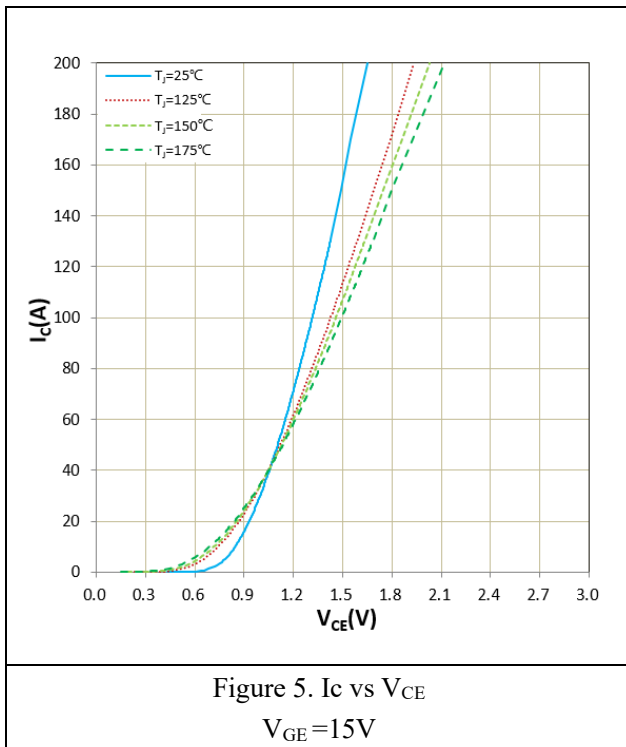


Figure 4. Switching time definition



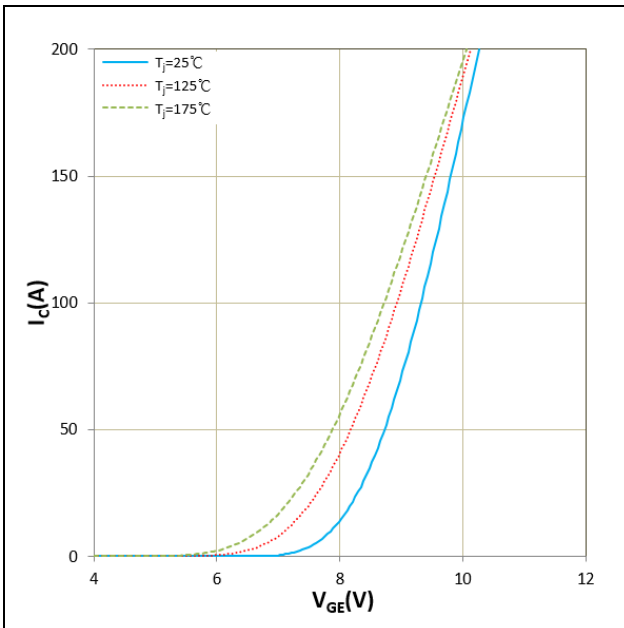


Figure 7. I_c vs V_{GE}
 $V_{CE}=20V$

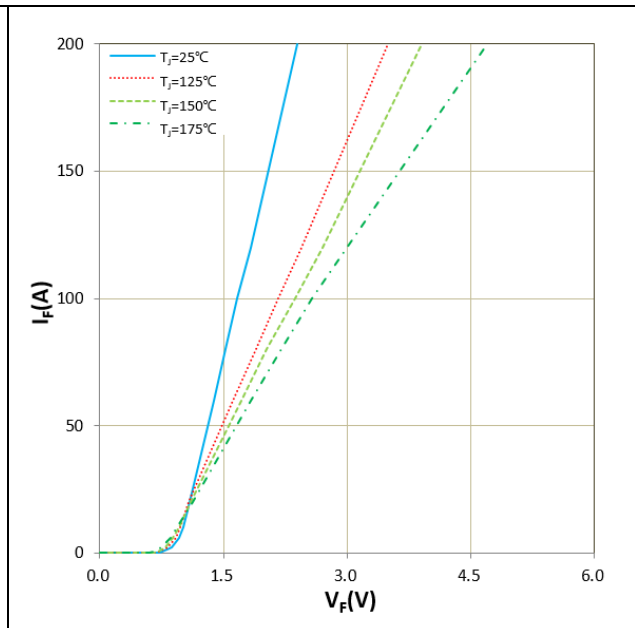


Figure 8. I_f vs V_f

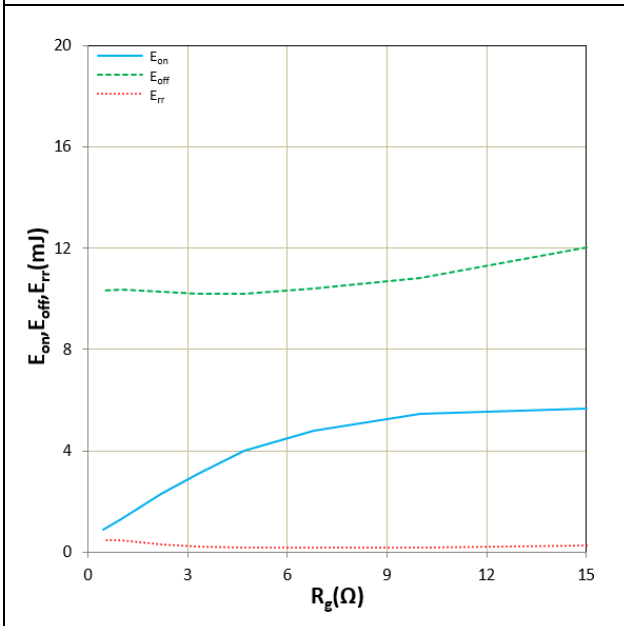


Figure 9. E_{on} , E_{off} , E_{rr} vs R_g (Typ)
 $V_{CC}=600V$, $V_{GE}=+15V/-8V$, $I_c=100A$, $T_j=25^\circ C$
Inductive Load

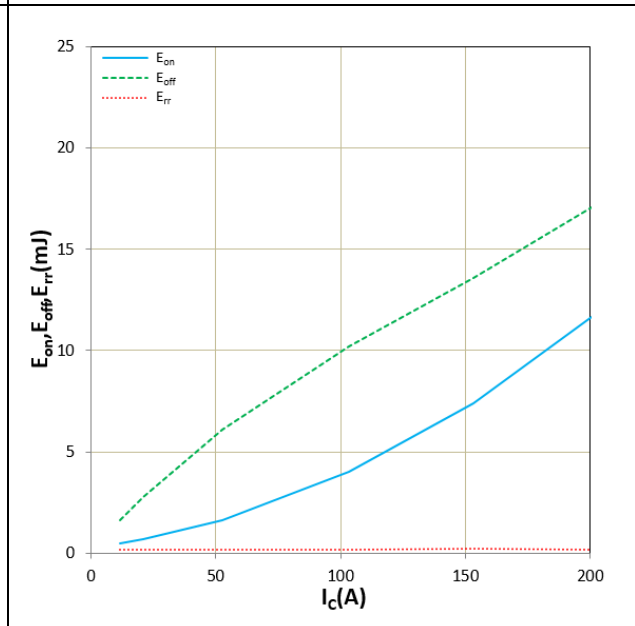


Figure 10. E_{on} , E_{off} , E_{rr} vs I_c (Typ)
 $V_{CC}=600V$, $V_{GE}=+15V/-8V$, $R_g=4.7\Omega$, $T_j=25^\circ C$
Inductive Load

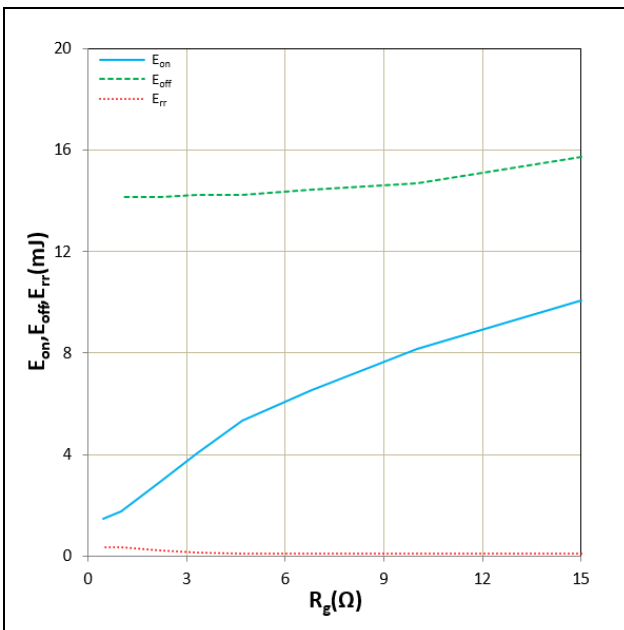


Figure 11. E_{on} , E_{off} , E_{rr} vs R_g (Typ)
 $V_{CC}=600V$, $V_{GE}=+15V/-8V$, $I_C=100A$, $T_j=125^\circ C$
 Inductive Load

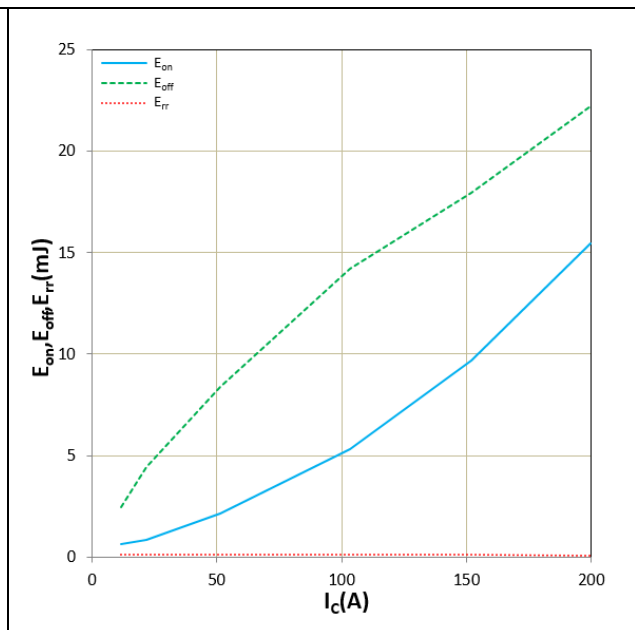


Figure 12. E_{on} , E_{off} , E_{rr} vs I_c (Typ)
 $V_{CC}=600V$, $V_{GE}=+15V/-8V$, $R_g=4.7\Omega$, $T_j=125^\circ C$
 Inductive Load

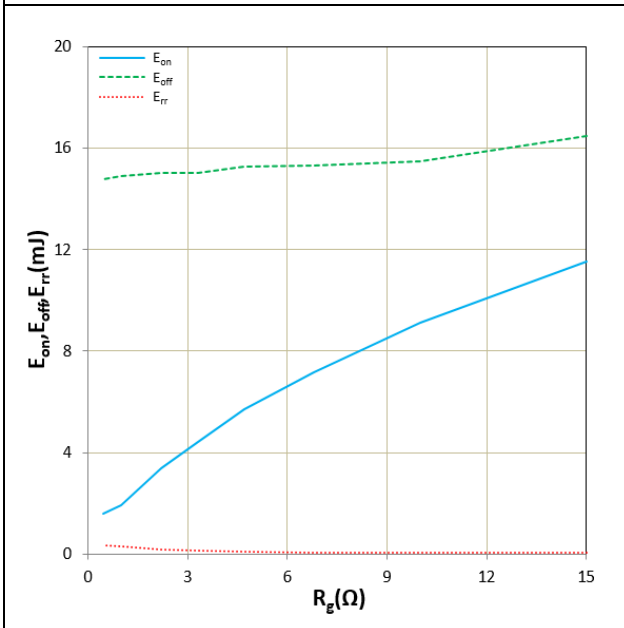


Figure 13. E_{on} , E_{off} , E_{rr} vs R_g (Typ)
 $V_{CC}=600V$, $V_{GE}=+15V/-8V$, $I_C=100A$, $T_j=150^\circ C$
 Inductive Load

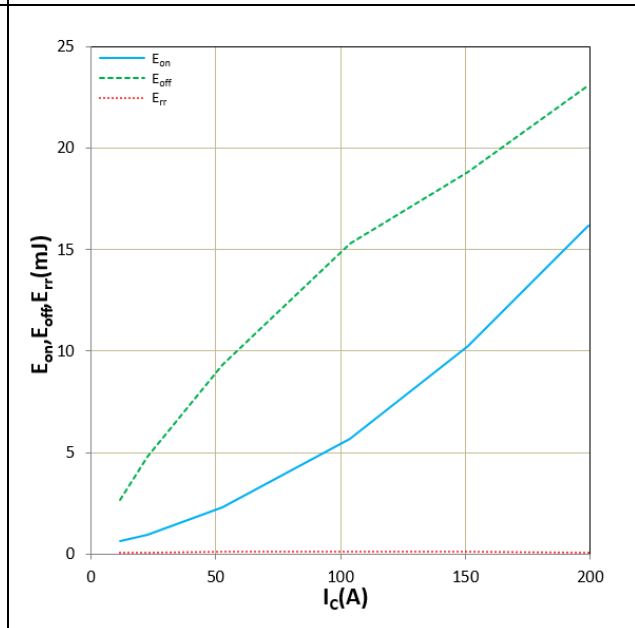


Figure 14. E_{on} , E_{off} , E_{rr} vs I_c (Typ)
 $V_{CC}=600V$, $V_{GE}=+15V/-8V$, $R_g=4.7\Omega$, $T_j=150^\circ C$
 Inductive Load

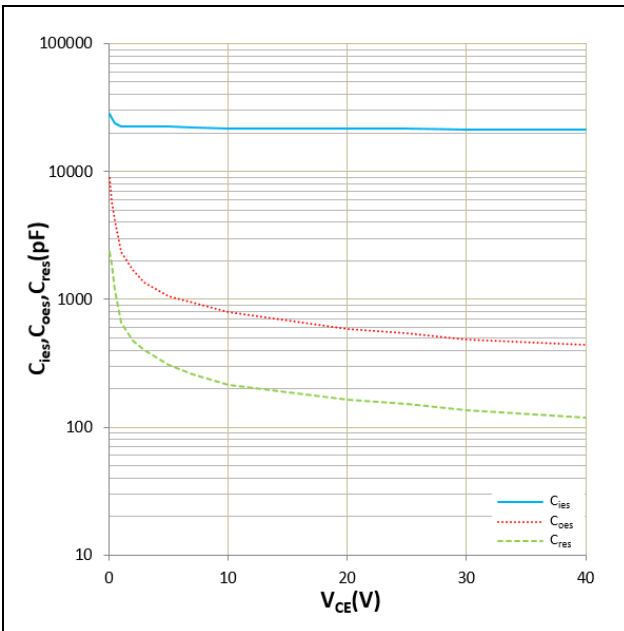


Figure 15. C_{ies} , C_{oes} , C_{res} vs V_{CE}
 $T_j=25^\circ\text{C}$, $f=1\text{MHz}$

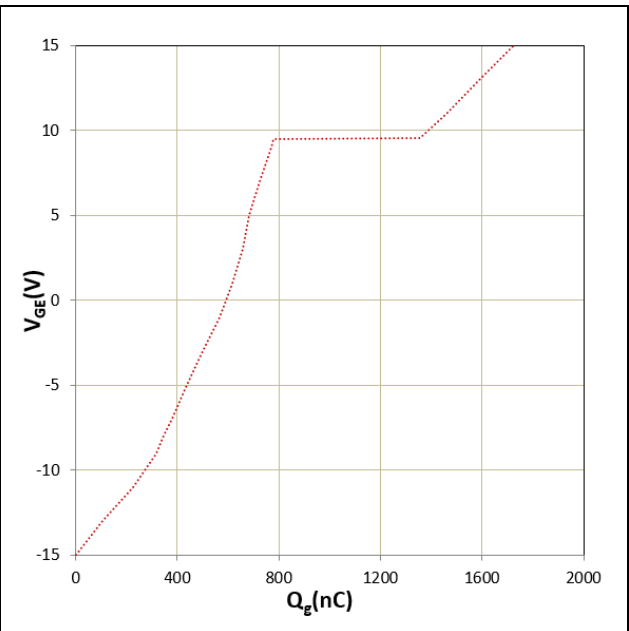


Figure 16. Gate charge
 $T_j=25^\circ\text{C}$

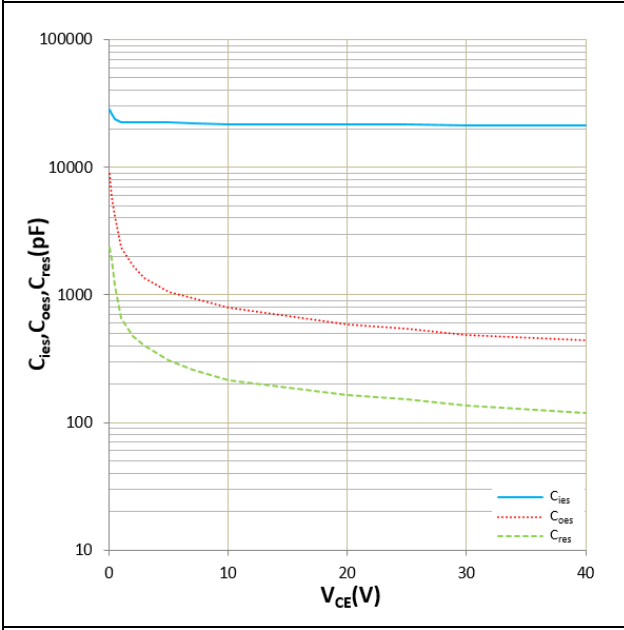


Figure 17. Transient thermal resistance

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